

### AMENDMENT TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

#### LISTING OF CLAIMS:

1. (Amended) A method of creating a stack of integrated circuits selectively connected to provide increased memory density in an application, the method comprising the steps of:

providing a carrier frame configured to have a plurality of members emergent into a window within the carrier frame;

applying a first portion of a solder-containing compound to the first side of the plurality of members;

placing a first packaged integrated circuit in contact with the plurality of members;

processing the first integrated circuit and the carrier frame with a heat source to create a first set of solder connections between the plurality of members and the first packaged integrated circuit;

applying a second portion of the solder-containing compound to the second side of the plurality of members of the carrier frame;

placing a second packaged integrated circuit in contact with the plurality of members;

processing the second integrated circuit and the carrier frame with a heat source to create a second set of solder connections between the plurality of members and the second integrated circuit.

2. (Currently Amended) The method of claim 1 in which ~~{plural iterations of the carrier frame are created in}~~ the carrier frame is provided from a carrier bed having a plurality of carrier frames.

3. (Previously Presented). The method of claim 1 in which the carrier frame and the first and second integrated circuits are further processed by separation of the plurality of members from the carrier frame.

4. (Cancelled).

5. (Cancelled).